

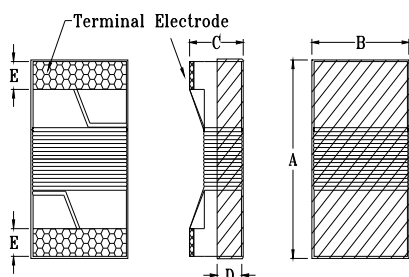
High Frequency Winding Type Chip Inductor SWI0805UV-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. High reliability -Reliability tests comply with AEC-Q200
8. Operating temperature-55~+125℃ (Including self - temperature rise)



2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI0805	2.29 max.	1.73 max.	1.52 max.	0.51 ref.	0.44±0.10

Unit:mm

3. Part Numbering

SWI	0805	U	V	-	2N8	S
A	B	C	D		E	F

A: Series

B: Dimension

C: Material

D: Category Code

E: Inductance

F: Inductance Tolerance

LxW

V=Vehicle

2N8=2.8nH

C=±0.2nH, S=±0.3nH, G=±2%, J=±5%, K=±10%

4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805UV-2N8□	2.8	C,S	0.1V/250M	80/1500	800	0.06	7900
SWI0805UV-3N0□	3.0	C,S	0.1V/250M	65/1500	800	0.06	7900
SWI0805UV-3N3□	3.3	C,S	0.1V/250M	50/1500	600	0.08	7900
SWI0805UV-5N6□	5.6	C,S	0.1V/250M	65/1000	600	0.08	5500
SWI0805UV-6N8□	6.8	C,J	0.1V/250M	50/1000	600	0.11	5500
SWI0805UV-7N5□	7.5	C,J	0.1V/250M	50/1000	600	0.14	4500
SWI0805UV-8N2□	8.2	C,J	0.1V/250M	50/1000	600	0.12	4700
SWI0805UV-10N□	10	G,J	0.1V/250M	60/500	600	0.10	4200
SWI0805UV-12N□	12	G,J	0.1V/250M	50/500	600	0.15	4000
SWI0805UV-15N□	15	G,J	0.1V/250M	50/500	600	0.17	3400
SWI0805UV-18N□	18	G,J	0.1V/250M	50/500	600	0.20	3300
SWI0805UV-22N□	22	G,J	0.1V/250M	55/500	500	0.22	2600

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805UV-24N□	24	G,J	0.1V/250M	50/500	500	0.22	2000
SWI0805UV-27N□	27	G,J	0.1V/250M	55/500	500	0.25	2500
SWI0805UV-33N□	33	G,J	0.1V/250M	60/500	500	0.27	2050
SWI0805UV-36N□	36	G,J	0.1V/250M	55/500	500	0.27	1700
SWI0805UV-39N□	39	G,J	0.1V/250M	60/500	500	0.29	2000
SWI0805UV-43N□	43	G,J	0.1V/200M	60/500	500	0.34	1650
SWI0805UV-47N□	47	G,J	0.1V/200M	60/500	500	0.31	1650
SWI0805UV-56N□	56	G,J	0.1V/200M	60/500	500	0.34	1550
SWI0805UV-68N□	68	G,J	0.1V/200M	60/500	500	0.38	1450
SWI0805UV-82N□	82	G,J	0.1V/150M	65/500	400	0.42	1300
SWI0805UV-91N□	91	G,J	0.1V/150M	65/500	400	0.48	1200
SWI0805UV-R10□	100	G,J	0.1V/150M	65/500	400	0.46	1200
SWI0805UV-R11□	110	G,J	0.1V/150M	50/250	400	0.48	1000
SWI0805UV-R12□	120	G,J	0.1V/150M	50/250	400	0.51	1100
SWI0805UV-R15□	150	G,J	0.1V/100M	50/250	400	0.56	920
SWI0805UV-R18□	180	G,J	0.1V/100M	50/250	400	0.64	870
SWI0805UV-R20□	200	G,J	0.1V/100M	50/250	400	0.68	860
SWI0805UV-R22□	220	G,J	0.1V/100M	50/250	400	0.70	850
SWI0805UV-R24□	240	G,J	0.1V/100M	44/250	350	1.00	690
SWI0805UV-R25□	250	G,J	0.1V/100M	45/250	350	1.20	660
SWI0805UV-R27□	270	G,J	0.1V/100M	48/250	350	1.00	650
SWI0805UV-R33□	330	G,J	0.1V/100M	48/250	310	1.40	600
SWI0805UV-R39□	390	G,J	0.1V/100M	48/250	290	1.50	560
SWI0805UV-R47□	470	G,J	0.1V/50M	33/100	250	1.70	375
SWI0805UV-R56□	560	G,J	0.1V/25M	23/50	230	1.90	340
SWI0805UV-R62□	620	G,J	0.1V/25M	23/50	210	2.20	220
SWI0805UV-R68□	680	G,J	0.1V/25M	23/50	190	2.20	188
SWI0805UV-R82□	820	G,J	0.1V/25M	23/50	180	2.35	215
SWI0805UV-1R0□	1000	G,J	0.1V/25M	20/50	170	2.5	100
SWI0805UV-1R2□	1200	G,J	0.1V/7.9M	18/25	170	2.5	100

7. Soldering and Mounting

7-1. Recommended PC Board Pattern

Chip size						Land Patterns For Reflow Soldering			
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	0805	2.29max	1.73max	1.52max	0.51 ref	0.44±0.1	2.80	1.25	1.78

